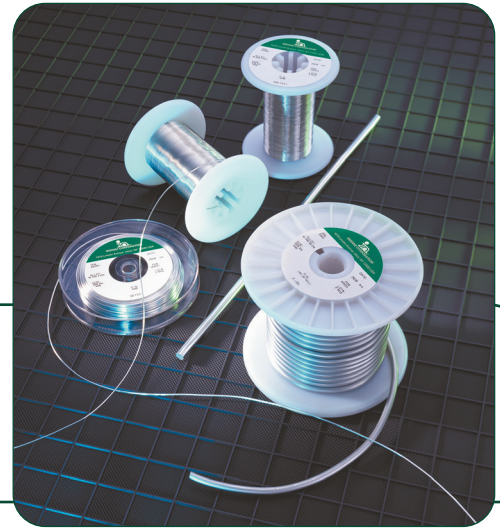


PRODUCT DATA SHEET

CORE 230 No-Clean Cored Wire Solder



Introduction

CORE 230 wire solder is cored with a no-clean flux that is fully compatible with Indium Corporation's NC-SMQ230 Pb-free solder paste. It contains a heat-stabilized rosin that provides excellent wetting and solder spread on various metallizations used in Pb-free assembly processes.

Features

- Optimized for use with Pb-free assembly processes
- Fast and excellent wetting to Pb-free surface finishes including immersion Ag, ENIG, and OSP
- Bellcore GR-78 compliant
- Resistant to charring
- Minimal spattering and low odor

Product Description

Spool Weight	.020" (0.5mm) or greater .015" (0.375mm) or smaller	500g or 1lb 125g or ¼lb
Flux Percentage	2.7–3.2% by weight	
Available Alloys	Per J-STD-006 Variation C 95.5Sn/3.8Ag/0.7Cu	

Wire Diameters

CORE 230 Wire Solder Length per Spool	
Wire Diameter	95.5Sn/3.8Ag/0.7Cu
.010" ± .001" (.254mm ± .03mm)	1,996ft (608m)
.015" ± .002" (.381mm ± .051mm)	2,087ft (636m)
.020" ± .002" (.508mm ± .051mm)	1,174ft (357.7m)
.032" ± .002" (.813mm ± .051mm)	459ft (139.8m)

Values are only approximate. Actual lengths will vary.

Bellcore and J-STD Tests and Results

Test	Result	Test	Result
J-STD-004 (IPC-TM-650)		Bellcore GR-78	
Flux Type Classification	ROL1	SIR	Pass
Flux Induced Corrosion (Copper Mirror)	Pass	<i>All information is for reference only. Not to be used as incoming product specifications.</i>	
Presence of Halide Fluoride Spot Test	Pass		
Corrosion	Pass		
SIR	Pass		

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices. All Indium Corporation's products and solutions are designed to be commercially available unless specifically stated otherwise.

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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Residue Removal

The flux in **CORE 230** is formulated for use in a no-clean assembly process. If cosmetics or the end use application requires removal of the post reflow residue, standard rosin-based residue removal techniques can be utilized. This includes, but is not limited to: spray-in air, immersion spray, vapor degreasing, or ultrasonic type cleaning processes.

Shelf Life

	Warranted	Practical*
Tin-Lead Alloys	10 years from DOM	Indefinite
Lead-Free Alloys	10 years from DOM	Indefinite
>85% High-Lead	2 years from DOM	Indefinite

*When stored at less than 40°C and less than 80% RH

Always store cored wire in a cool, dry environment. The main causes of degraded cored wire reflow performance are the buildup of a thick oxide layer on the surface of the wire, caused by prolonged exposure to higher than normal temperature and humidity conditions, or the buildup of lead carbonate on high-lead (>85%) alloy cored wire shipped or stored under very high-humidity conditions.

Technical and Customer Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Materials Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon, and paste. Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

Safety Data Sheets

Please refer to the SDS document within the product shipment, or contact our local team to receive a copy.



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